



Data Sheet

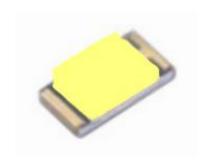
Customer:	
Part No:	L-SP192CW1D-A15-4T
Sample No:	
Description:	1608 Warm 6000-7000k WHITE
Item No:	

Customer						
Check Inspection Approval Date						





SMD Type **Top view Package L-SP192CW1D-A30-4T



Features

- . 0603 package
- . Top view LED
- . Compatible with infrared and vapor phase reflow solder process.
- . Wide viewing angle
- . Pb-free
- . RoHS compliant

Description

- . The Ciellight 192 package has high efficacy, high power consumption, wide viewing angle and a compact form factor.
 - . These features make this package an ideal LED for all lighting applications.

Applications

- . General lighting
- . Decorative and Entertainment Lighting
- . Indicators
- . Automotive Telecommunication
- . Switch lights

Device Selection Guide

Chip Material	Emitted Color	Resin Color
InGaN	White	Yellow Diffused





Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Unit
Continuous Forward Current	I_F	25	mA
Operating Temperature	T_{opr}	-40 ∼ +85	$^{\circ}\! \mathbb{C}$
Storage Temperature	T_{stg}	-40 ~ +100	${\mathbb C}$
Peak Forward Current (Duty 1/10@1ms)	I_{FP}	60	mA
Soldering Temperature*1	Т	Reflow Soldering : 260 ℃	for 10 sec.
Soldering Temperature.	T_{sol}	Hand Soldering: 350 ℃	for 3 sec.
Power Dissipation at(or below) 25°C Free Air Temperature	P_d	95	mW
23 Criec All Temperature			
Electrostatic Discharge(HBM)	ESD	2000	V

Notes: *1: Soldering time ≤ 5 seconds

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Condition
Forward Voltage	V_{F}	2.7		3.3	V	I _F =20mA
Reverse Current	I_R			10	μΑ	V _R =5V
Luminous Intensity	Iv	640		920	mcd	I _F =20mA
Viewing Angle	$2\theta_{1/2}$		120		deg	I _F =20mA

Notes:

- 1. Tolerance of Luminous Intensity $\pm 10\%$. 2. Tolerance of Forward Voltage : ± 0.1 V.

Bin Range of Luminous Intensity

Bin Code	Min	Max	Unit	Condition
Sa1	700	765		
Sa2	765	840		
Ta1	840	920	mcd	$I_F=20mA$
Ta2	920	1050	_	
Ua1	1050	1200		

Note:

Tolerance of Luminous Intensity: ±10%.





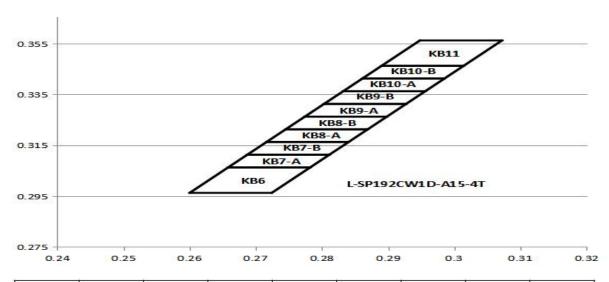
Bin Range of Forward Voltage

Bin Code	Min	Max	Unit	Condition
27	2.7	2.8		
28	2.8	2.9		
29	2.9	3.0	V	$I_F=20mA$
30	3.0	3.1	V	IF-20IIIA
31	3.1	3.2		
32	3.2	3.3		

Note:

Tolerance of Forward Voltage: ± 0.1 V.

Bin Range of Chromaticity Coordinates



	0.2600	0.2963	VD7 A	0.2658	0.3063	КВ7-В	0.2687	0.3113
VDC	0.2724	0.2963		0.2782	0.3063		0.2811	0.3113
KB6	0.2782	0.3063	NDI-A	0.2811	0.3113		0.284	0.3163
	0.2658	0.3063	0. 2963 KB7-A 0. 2782 0. 3063 KB7-B 0. 2811 0. 3113 0. 3063 0. 2811 0. 3113 0. 3063 0. 2687 0. 3113 0. 3063 0. 2687 0. 3113 0. 3063 0. 2687 0. 3113 0. 3063 0. 3213 0. 3213 0. 3213 0. 3213 0. 3213 0. 32898 0. 3263 0	0.2716	0.3163			
	0.2716	0.3163		0.2745	0.3213	KB9-A	0.2774	0.3263
ZDO A	0.284	0.3163	VDO D	0.2869	0.3213		0. 2898	0.3263
KB8-A	0.2869	0.3213	ND9-D	0.2898	0.3263		0.2927	0.3313
	0.2745	0.3213		0.2774	0.3263		0. 2927 0. 2803 0. 2861 0. 2985	0.3313
	0.2803	0.3313	PD10 A	0.2832	0.3363	VD10 D	0.2861	0.3413
KBO B	0.2927	0.3313		0.2956	0.3363		0. 2985	0.3413
KB9-B	0.2956	0.3363	VPIO-W	0.2985	0.3413	VPIO-P	0.3014	0.3463
	0.2832	0.3363		0.2861	0.3413		0.289	0.3463
	0.289	0.3463						
KB11	0.3014	0.3463		2			8	
KDII	0.3072	0.3563						
	0.2948	0.3563				1 [

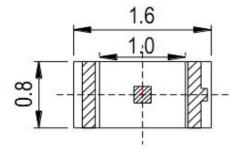
Note:

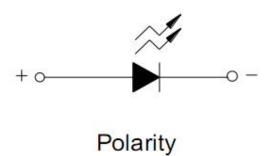
- 1. The value is based on driving current by 20mA.
- 2. Tolerance of Chromaticity Coordinates: ±0.01

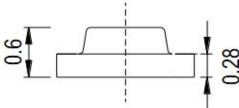


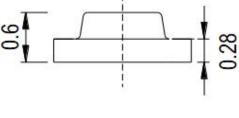


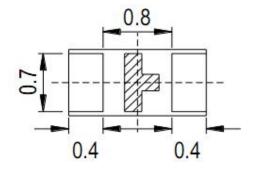
Package Dimensions



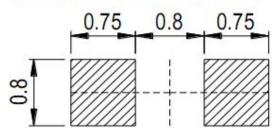








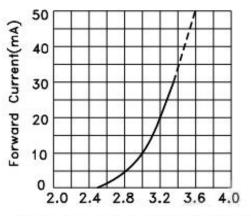
Recommended Solder Pad



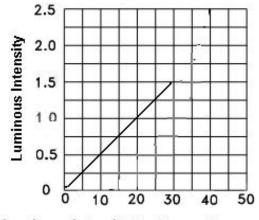
Note: Tolerance unless mentioned is ± 0.1 mm,Unit = mm.



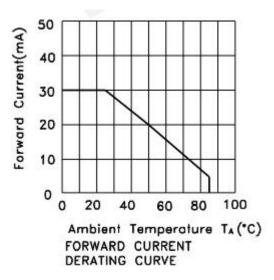


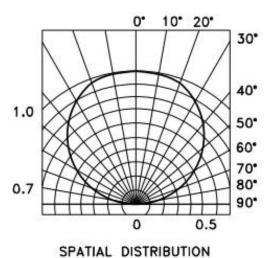


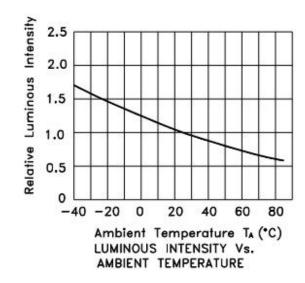
Forward current Vs. Forward voltage

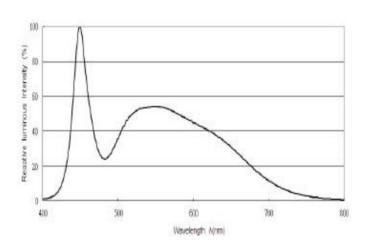


Luminous Intensity Vs. Forward current













Label Form Specification

CPN: Customer's Production Number

P/N : Production Number QTY: Packing Quantity

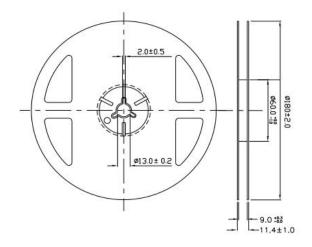
CAT: Ranks

HUE: Peak Wavelength

REF: Reference

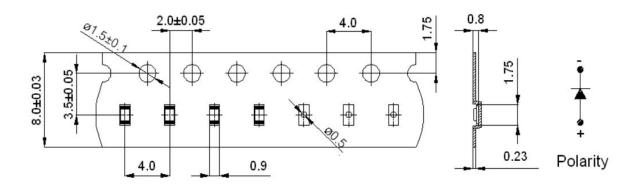
LOT No: Lot Number

Reel Dimensions



Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

Carrier Tape Dimensions:(Quantity: 4000pcs/reel)



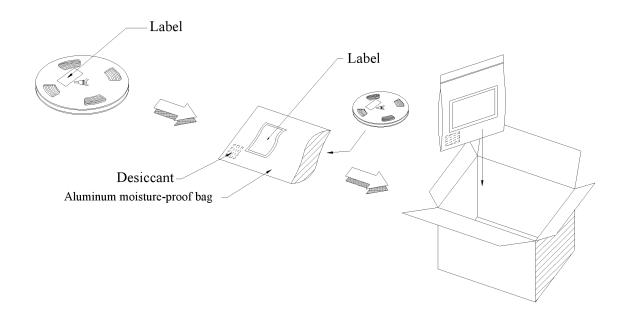
Note:

- 1. Tolerance unless mentioned is ± 0.1 mm, Unit = mm.
- 2. Minimum packing amount is 1000/2000 pcs per reel.





Moisture Resistant Packing Process



Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level: 90%

LTPD: 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp.: 260°C/10sec.	6 Min	22 PCS	0/1
2	Thermal Shock	H: +100°C 5min \int 10 sec L: -10°C 5min	300 Cycles	22 PCS	0/1
3	Temperature Cycle	H: +100°C 15min ∫ 5 min L: -40°C 15min	300 Cycles	22 PCS	0/1
4	High Temperature/Humidity Reverse Bias	Ta=85℃,85%RH	1000 Hrs.	22 PCS	0/1
5	Low Temperature Storage	Ta=-40 ℃	1000 Hrs.	22 PCS	0/1
6	High Temperature Storage	Ta=100°C	1000 Hrs.	22 PCS	0/1
7	DC Operation Life	Ta=25 °C IF = 20 mA	1000 Hrs.	22 PCS	0/1





Precautions For Use

1. Over-current-proof

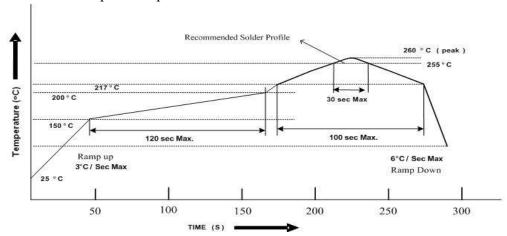
Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 40°C or less and 90%RH or less.
- 2.3 The LEDs should be used within a year.
- 2.4 After opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.
- 2.5 The LEDs should be used within 168 hours (7 days) after opening the package
- 2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following J-STD-33 Standard.

3. Soldering Condition

3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.